

Notice of References Cited		Application/Control No. 10/582,295	Applicant(s)/Patent Under Reexamination VIVIENNE ET AL.	
		Examiner BOBBY RAMDHANIE	Art Unit 1797	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-			
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	J	US-			
	K	US-			
	L	US-			
	M	US-			

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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.